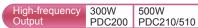
# **Plasma Cleaner (Parallel Electrode)**

Plasma Surface Treatment Device

# PDC200/210/510



Stage size

## Small and compact, suitable for R&D purposes

#### Features

- Simple and compact plasma surface treatment device
- RIE (Reactive Ion Etching) Plasma mode, with DP (Direct Plasma) mode as option (PDC200/210)
- Excellent electrode structure for plasma uniformity
- Simple touch panel system

#### **Applications**

- Plasma processing of CSP, BGA, COB substratum
- Removal of organic films and metal oxidized films
- Dry cleaning of printed circuit board
- Surfactant process
- LED assembly
- For R&D

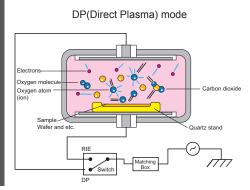


PDC210

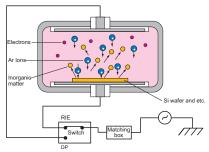
#### Chamber



### **Diagram**



#### RIE(Reactive Ion Etching) mode



#### Specifications

Product code	328210	328211	215054
Model	PDC200	PDC210	PDC510
Plasma mode	RIE (DP mode option)		RIE/DP selectable
Electrode structure	Parallel flat stage plate		
Vacuum gauge	Capacitance manometer		
High frequency output	Max 300W	Max 500W	
Oscillation frequency	13.56MHz Quartz oscillator		
Output setting method	Manual setting on LCD touch panel		
Matching method	Auto tuning		
Chamber size	W400×D250×H150mm		W500×D300×H200mm
Stage size	W250×D170mm		W400×D200mm
Chamber material	Aluminum		
Reaction gas	2 systems (Argon, Oxygen)		
Purge gas	Nitrogen or dry air		
Reaction gas flow control	Flow meter	Mass flow controller	
Rotary vacuum pump	Approx. 345L/min. (Option)	Approx. 345L/min. (Provided)	Approx. 500L/min. (Provided)
External dimensions	W540×D600×H600mm	W540×D600×H600mm	W700×D700×H1,285mm
Weight	Approx. 100kg	Approx. 105kg	Approx. 180kg
Power source (50/60Hz)	AC115V / AC220V Single phase with step-down transformer	AC220V~AC415V Three phase with step-down transformer	

External dimensions do not include projections.